



Material Content Data Sheet



Sales Product Name		TLE6251-3G		Issued		19. July 2018		
MA#		MA001465864						
Package		PG-DSO-14-1		Weight*		143.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.050	3.52	3.52	35164	35164
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		420	
	non noble metal	iron	7439-89-6	1.207	0.84		8404	
wire	non noble metal	copper	7440-50-8	49.007	34.13	35.02	341256	350185
	noble metal	gold	7440-57-5	0.196	0.14	0.14	1367	1367
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.12		1168
plastics		epoxy resin	-	7.717	5.37		53740	
	inorganic material	silicondioxide	60676-86-0	76.000	52.92	58.41	529219	584127
leadfinish	non noble metal	tin	7440-31-5	1.241	0.86	0.86	8645	8645
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7171	7171
glue	plastics	acrylic resin	-	0.421	0.29		2935	
	noble metal	silver	7440-22-4	1.494	1.04	1.33	10406	13341
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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